



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TYN612MRG	7GDZ*P1G126T	A	3068	2017-01-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7GDZ*P1G126T					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.635	mg	supplier	die	Silicon (Si)	7440-21-3		2.866	mg	788446	1508
				supplier	metallization	Aluminium (Al)	7429-90-5		0.100	mg	27510	53
				supplier	metallization	Gold (Au)	7440-57-5		0.011	mg	3026	6
				supplier	Passivation	Silicon Oxide	7631-86-9		0.026	mg	7152	14
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.016	mg	4402	8
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1651	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	7153	16
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.584	mg	160660	307
Leadframe	Copper & its alloys	1253.534	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.375	mg	998278	658618
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	391	258
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	31	21
Soft solder	Solder	3.700	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.533	mg	954865	1859
				supplier	solder	Silver (Ag)	7440-22-4		0.093	mg	25135	49
				supplier	solder	Tin (Sn)	7440-31-5		0.074	mg	20000	39
Bonding wires	Other inorganic materials	2.941	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.941	mg	1000000	1548
Encapsulation	Other Organic Materials	629.828	mg	supplier	mold compound	Silica, vitreous	60676-86-0		547.950	mg	870000	288395
				supplier	mold compound	Epoxy resin	25068-38-6		62.983	mg	100000	33149
				supplier	mold compound	Phenol resin	29690-82-2		15.746	mg	25000	8287
				supplier	mold compound	Carbon Black	1333-86-4		3.149	mg	5000	1657
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348